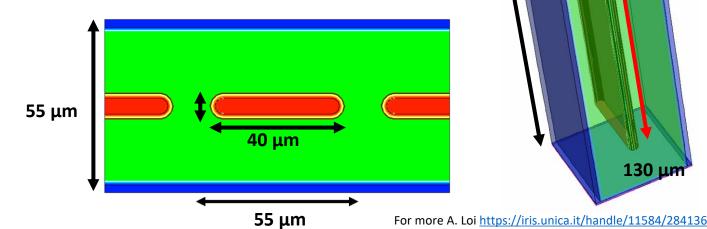
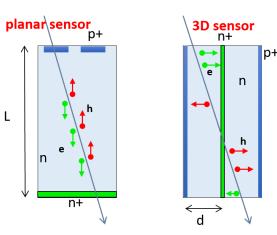


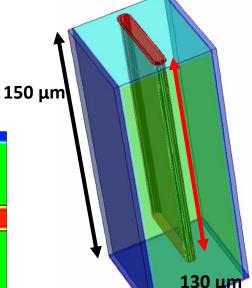
Technology and design

- The approach within TimeSPOT was to use 3D silicon (and Diamond) sensors to achieve fast timing
 - Reducing inter-electrode distance
 - Reducing charge collection time ٠
 - As well improving intrinsic time resolution
 - Increasing radiation hardness ٠
- The final geometry selected for the fast timing 3D sensor is the "parallel-trench"
 - Already produced in two batches (2019 and 2021) by FBK

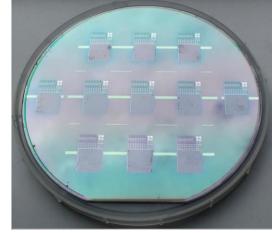




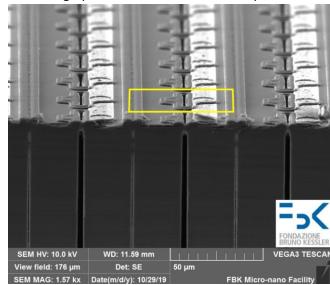
TCAD model of the selected geometry



First TimeSPOT batch, produced by FBK



Cut along a parallel trench device based strip sensor



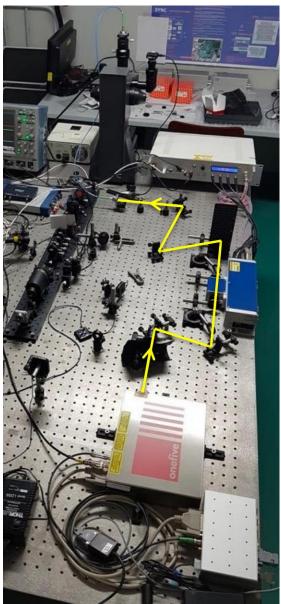
IFD 2022 - Time resolution of 3D silicon sensors with trench electrodes

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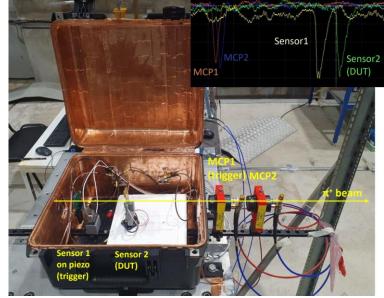
TimeSPOT TCT setup



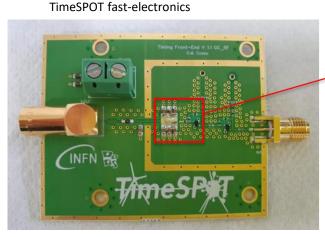
Measurements

- Sensor has been characterised
 - Test beams (10/2019, 10/2021 and 5/2022) →
 - Intrinsic time resolution
 - Performance by tilting the device
 - Sensor Efficiency
 - Performance after radiation
- Customised fast readout has been developed in order to fully explore sensor performance

Test beam setup for intrinsic time resolution characterisation

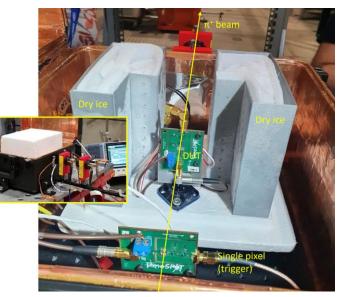


Dry ice enclosure for rad hard measurements





Single pixel test device

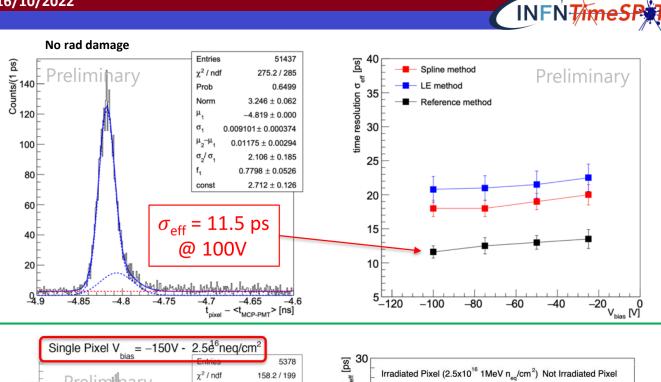


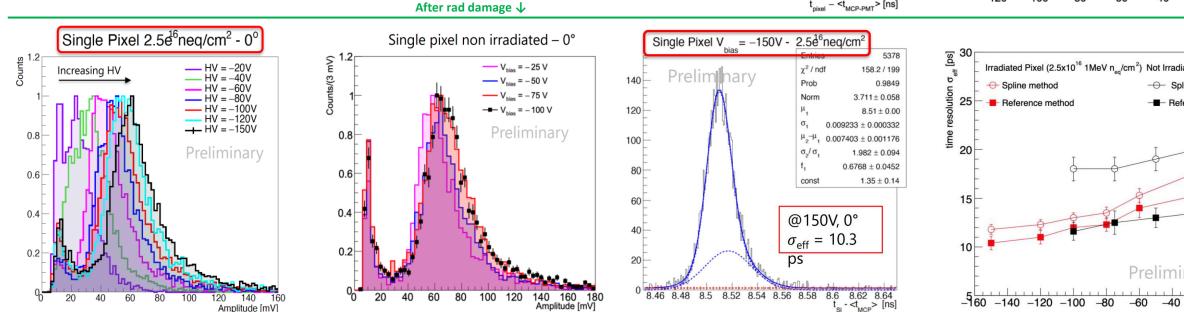
IFD 2022 - Time resolution of 3D silicon sensors with trench electrodes



Results (1)

 Intrinsic time Resolution before and after radiation damage above 10¹⁶ n_eq





With a slightly larger bias voltage (w.r.t. non-irradiated pixel working point) the signal amplitude of irradiated sensors is recovered!

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IFD 2022 - Time resolution of 3D silicon sensors with trench electrodes

---- Spline method

Preliminary

-40

-60

Reference method

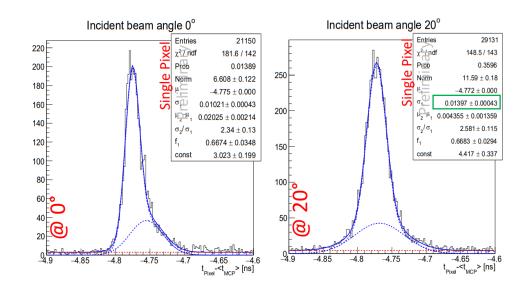
For more info: A. Lampis

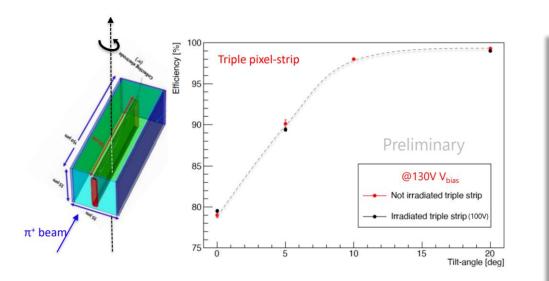
https://indico.cern.ch/event/1120714/contributions/4867208/attachments/2472539/4242526/Andrea Lampis iworid2022.pdf https://indico.cern.ch/event/1127562/contributions/4954529/attachments/2511647/4317271/TimeSPOT TWEPP2022 Final.pdf

10

Results (2) and outlook

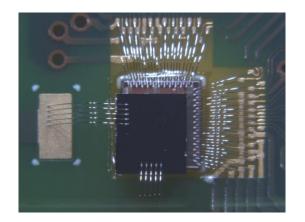
- Sensor behaviour has been studied also by tilting it
 - ToA distribution at 20° becomes more gaussian
 - The inefficiency (at normal incidence) due to the deadarea of the trenches is fully recovered by tilting the sensors around the trench axis
 - It also works for irradiated sensors





Outlook:

 32x32 pixel matrix has been bump-bonded on the TimeSPOT-1 ASIC and currently tested. Future 4D tracking detector and its components are under test and caracterisation (more about it on Lorenzo's slides)



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